

MAR 07 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
(Case No. 207.008-US)

IFW

In the Application of: Lutz et al.

) Group Art Unit: 2822

Serial No: 10/627,237

) Examiner: Prenty, Mark V.

Filed: July 25, 2003

Title: Anchors for Microelectromechanical Systems  
Having an SOI Substrate, and Method for  
Fabricating Same

I hereby certify that this correspondence  
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Michiko Sikes  
Signature

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

SIXTH INFORMATION DISCLOSURE STATEMENT

Dear Sir:

Submitted herewith are two (2) sheets of a modified Form PTO-1449. Electronic copies of the U.S. patents and published U.S. patent applications identified on the attached Form PTO-1449 are found on the attached compact disc ("CD"). A paper copy of each foreign document and publication cited on the attached Form PTO-1449 is also submitted.

Notably, U.S. Published Patent Application 2004-0065932 is the U.S. counterpart of International Application No. WO 01/46066, both of which are identified in the attached Form PTO-1449. That published application was cited in U.S. Patent Application Serial No. 10/455,555, entitled "Microelectromechanical Systems having Trench Isolated Contacts, and Methods for Fabricating Same".

It is respectfully requested that the Examiner make his/her consideration of these documents formally of record with the next Office Action.

Respectfully submitted,

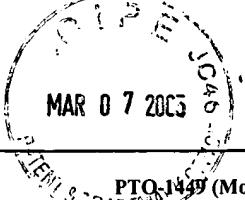


Neil A. Steinberg, Reg. No. 34,735  
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Date: March 3, 2005

MAR 07 2003

Sheet 1 of 2

 <b>U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE</b>  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>	ATTY. DOCKET NO. <b>207.008-US</b>	SERIAL NUMBER <b>10/627,237</b>
	<b>APPLICANT(S)</b> <b>Lutz et al.</b>	
	FILING DATE <b>July 25, 2003</b>	GROUP ART UNIT <b>2822</b>

**U.S. PATENT DOCUMENTS**

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE
	4,849,071	7/1989	Evans et al.			
	4,945,769	8/1990	Sidner et al.			
	5,445,991	8/1995	Lee			
	5,470,797	11/1995	Mastrangelo			
	5,616,514	4/1997	Muchow et al.			
	6,521,508	2/2003	Cheong et al.			
	2004/0016989	1/2004	Ma et al.			
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	5,139,624	8/1992	Searson et al.			
	5,338,416	8/1994	Micak et al.			
	6,808,954	10/2004	Ma et al.			
	2004-0065932	4/2004	Reichenbach et al.			

**FOREIGN PATENT DOCUMENTS**

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION YES/NO

**OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)**


<b>EXAMINER</b>	<b>DATE CONSIDERED</b>
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**EXAMINER:** Initial citation if reference was considered. Draw line through citation if not in conformance to MPEP 609 and not considered. Include copy of this form with next communication to applicant.

<b>PTO-1449 (Modified)</b>  <b>U.S. DEPARTMENT OF COMMERCE</b> <b>PATENT AND TRADEMARK OFFICE</b>  <b>INFORMATION DISCLOSURE STATEMENT</b> <b>BY APPLICANT</b>	ATTY. DOCKET NO. <b>207.008-US</b>	SERIAL NUMBER <b>10/627,237</b>
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**FOREIGN PATENT DOCUMENTS**

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION YES/NO
	WO 01/46066	6/2001	PCT			
	GB 2 198 611	6/1988	Great Britain			
	WO 97/49475	12/1997	PCT			
	EP 0 451 992	10/1991	European			

**OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)**

	"Permeable Polysilicon Etch-Access Windows for Microshell Fabrication", Lebouitz K S et al., International Conference on Solid-State Sensors and Actuators and Eurosensors, 25 June 1995 (1996-06-25), pp. 224-227
	"Porous Polycrystalline Silicon: A New Material for MEMS", Anderson R C et al., Journal of Microelectromechanical Systems, March 1994, USA, vol. 3, no. 1, pp.10-18
	"Vacuum Encapsulation of Resonant Devices Using Permeable Polysilicon", Lebouitz et al., 1999 IEEE, pp.470-475
	"Laterally Grown Porous Polycrystalline Silicon: A New Material for Transducer Applications", Anderson et al., 1991 IEEE, pp.747-750

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